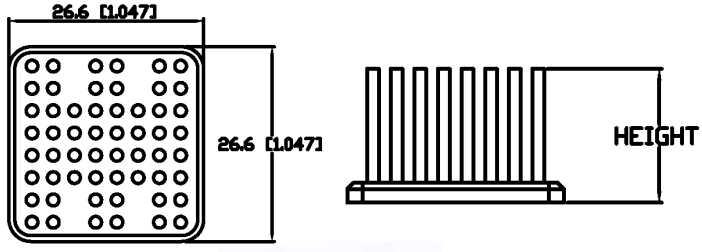
Model : CMBA022727 Series

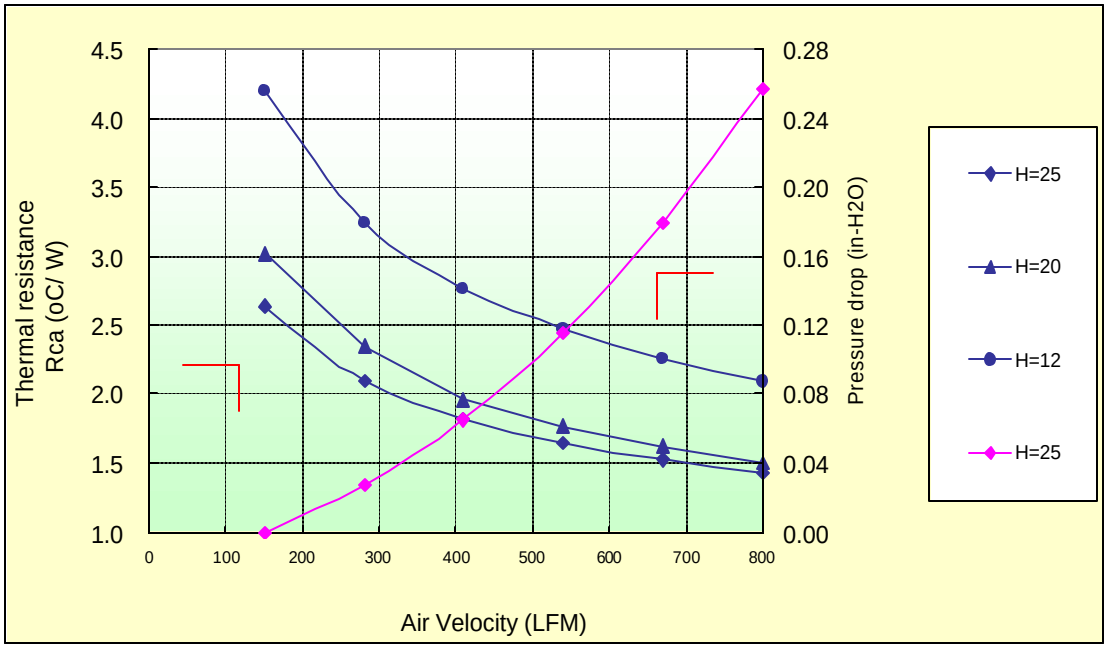
BGA Heat Sink For 27x27 Chip set

Specification



1.Material : Al 6063
2.Dimension :
Foot print : 27x27mm
Height : 12,15,18,21,23,28,33 mm
Base (thickness) : 2.6mm

3.Finish: Black Anodize
4.Chip set package thickness and clip color
3.3+/-0.25mm - Yellow clip
1.7+/-0.25mm - Blue clip
0.8+/-0.25mm - Orange clip
5.Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : T710 or others

Performance

Heat Source (LxW)	15x15